

Buffer Overflow in WL18xx MCP Driver



Summary

The TI WiLink WL18xx MCP driver does not limit the number of information elements (IEs) of type XCC_EXT_1_IE_ID or XCC_EXT_2_IE_ID that can be parsed in a management frame. Using a specially crafted frame, a buffer overflow can be triggered that can potentially lead to remote code execution.

Vulnerability

TI PSIRT ID

TI-PSIRT-2022-120160

CVE ID:

CVE-2023-29468

CVSS Score

The CVSS base score for this issue can range from 8.8 to 9.6. The higher base score reflects a Confidentiality and Integrity impact of *High*. However, some systems can have a Confidentiality or Integrity Impact of *Low* depending on the characteristics of the host processor executing the WL18xx MCP driver and whether the disclosure or modification of the memory that can be accessed represents a direct or serious loss.

CVSS vector

- High Score (9.6): [CVSS:3.1/AV:A/AC:L/PR:N/UI:N/S:C/C:H/I:H/A:H](#)
- Low Score (8.8): [CVSS:3.1/AV:A/AC:L/PR:N/UI:N/S:C/C:L/I:L/A:H](#)

Affected Products

- WILINK8-WIFI-MCP8 version 8.5_SP3 and earlier

Potentially Impacted Features

An attacker within wireless range of a potentially vulnerable device can gain the ability to overwrite memory of the host processor executing the MCP driver.

Suggested Mitigations

In MCP8.5_SP3\WiLink\UWD\src\Services\mlmeParser.c, include the following code starting at line 720:

```
if( rsnIeIdx >= 3 )
{
TRACE(pHandle->hReport, REPORT_SEVERITY_ERROR, "MLME_PARSER: Number of RSN IEs exceeds 3\n");
return TI_NOK;
}
```

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